

***Now Available!***

---

# THE WORLDWIDE IC PACKAGING MARKET

***2018 EDITION***

**The Most Comprehensive Report Available  
On The Global IC Packaging Industry**

## Report Highlights

- **Industry Overview**
  - ◆ **Economic Overview**
  - ◆ **Semiconductor Industry Analysis**
  
- **Worldwide Semiconductor Device Market Forecasts, 2016–2022**
  - ◆ **By Unit Shipments and Revenues**
  - ◆ **By Packaging Type**
  - ◆ **By Application**
  - ◆ **By Major World Region**
  
- **Worldwide IC Packaging Market Forecasts, 2016-2022**
  - ◆ **By Unit Shipments, Revenues and ASP**
  - ◆ **By Semiconductor Product**
  - ◆ **By I/O Range**
  
- **OSAT IC Packaging Market Forecasts, 2016–2022**
  - ◆ **IC Packaging Type by Unit Shipments, Revenues and ASP**
  - ◆ **Competitive Rankings**
  - ◆ **Company Profiles**

**New Venture Research Corp.**

337 Clay St., Suite 101

Nevada City, CA 95959

[www.newventureresearch.com](http://www.newventureresearch.com)

*A Technology Market Research Company*

[info@newventureresearch.com](mailto:info@newventureresearch.com)

Tel: (530) 265-2004

Fax: (530) 265-1998

# The Worldwide IC Packaging Market, 2018 Edition

## Synopsis

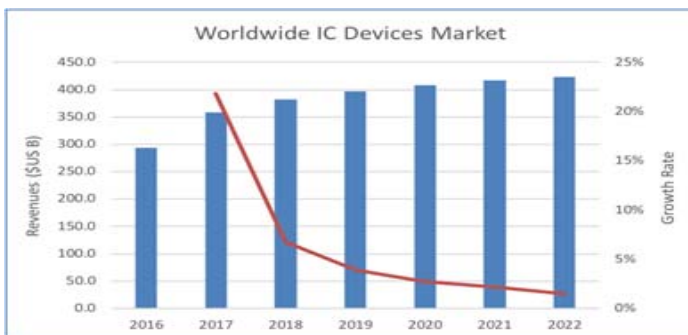
The Worldwide IC Packaging Market, 2018 Edition, a new report from New Venture Research (NVR), examines the global marketplace of integrated circuits (ICs) and the many packaging designs developed for ICs. This comprehensive report presents detailed analysis of a vast and vibrant market that exceeded \$358 billion in 2017. The nearly 500-page report provides insightful analysis of major market trends affecting the semiconductor industry, and presents dozens of tables and figures quantifying both the semiconductor device and IC packaging markets. The report provides extensive and detailed quantitative analysis with forecasts for unit shipments, revenues and package pricing for 31 separate semiconductor device types as well as 14 major packaging categories comprising 44 IC packaging market segments. Virtually every table presents two years of historical data for 2016 and 2017, and five-year forecasts from 2018 through 2022. In addition, numerous graphical figures provide an alternative perspective for understanding the underlying data.

The report is arranged into seven chapters focused on four major topics of discussion. Following an Introductory chapter (Chapter 1) and an Executive Summary (Chapter 2), Chapter 3, "Worldwide Electronics Industry Outlook," examines broad economic trends and the global electronics industry, specifically looking at products that are helping drive the expanding demand for semiconductors and IC packaging technologies. Markets covered includes communications products, computers and peripherals, and consumer products, as well as products for industrial, medical, automotive and commercial aviation and defense sectors.

In Chapter 4, "Semiconductor Device Market Analysis," the report analyzes each semiconductor device type with forecasts provided for unit shipments and revenues presented in terms of function, packaging types, applications and major world regions. Chapter 5, "IC Packaging Market Analysis," examines the IC packaging market in terms of unit shipments, revenues and package pricing for each packaging market segment in terms of semiconductor device type and I/O count. The chapter also provides a short overview of advanced packaging products adapted from NVR's companion report Advanced IC Packaging Technologies, Materials and Markets, 2017 Edition.

Chapter 6, "OSAT Market and Strategy Analysis," focuses on the outsourced semiconductor assembly and test (OSAT) company market segment, vendors who specialize in providing IC packaging and testing services to other companies in the industry. Consisting of more than 100 companies worldwide, the OSAT market segment accounts for a significant and growing sector of the semiconductor market. The report looks not only at the size of the OSAT market, but discusses the various strategies for success shared by the leading competitors. Finally, Chapter 7, "OSAT Company Profiles," presents concise profiles of 40 OSAT companies, providing a cross-section of both large and small competitors. Each profile includes an overview of the company, as well as details of their IC packaging product lines.

**The Worldwide IC Packaging Market, 2018 Edition** continues NVR's leadership position in analyzing semiconductor device markets and IC packaging products and technologies. This report is an effective and economical tool for any company interested in competing in the semiconductor industry as an aid in assessing the present and future of this dynamic industry. The report sells for \$3995 and is delivered by email as a single-user PDF file. Extra single-user licenses sell for \$500 each and a corporate license is available for an additional \$1500. With the purchase of the report, an Excel spreadsheet containing every table and graphic may be obtained for an additional \$1000 and a printed copy for \$250.



## About The Author

**Jerry Watkins** is an independent senior analyst with more than 20 years of direct experience in the field of market research and consulting. He has worked for leading research companies such as Frost & Sullivan, Lucid Information Services, and NSI Research, both in management and as a writer. Mr. Watkins has authored many syndicated reports, previously in the telecommunications and office automation sectors and more recently in the semiconductor industry, writing on subjects that include IC packaging and merchant embedded computing. He holds two university degrees, including a B.A. in History and an M.A. in International Studies, but he feels that market research best fulfills his lifelong passion for inquiry into difficult subject matter and making it comprehensible to a wide audience. Mr. Watkins has lived and worked in Silicon Valley for most of his career.

# The Worldwide IC Packaging Market, 2018 Edition

## Table of Contents

### Chapter 1: Introduction

### Chapter 2: Executive Summary

### Chapter 3: Worldwide Electronics Industry Outlook

#### Global Economic Outlook

Recent Economic Trends

World GDP

Impact on Semiconductor Market

Trends to Watch in 2018 and Beyond

#### Global Electronics Market

- Communications Markets, including: Cellular Handsets, LANs, DSL & Cable Modems, Carrier-class Equipment
- Computers Markets, including: PCs, Tablets, Servers, Storage Systems, Monitors, Printers
- Consumer Markets, including: TVs, Set-top Boxes, Digital Cameras, Personal Navigation Devices
- Industrial Markets, including: Process Control, Test & Measurements, Other Industrial
- Medical Markets, including: Medical Diagnostics, Therapeutic, Monitoring & Surgical
- Automotive Markets
- Commercial Aviation, Defense and Other Transportation Markets

### Chapter 4: Semiconductor Device Market Analysis

#### Worldwide Semiconductor Device Market

Total Market Forecasts

IC Application Forecasts

Regional Market Trends

*Covers: Consumer, Transportation, Computer Communications, Industrial & Other*

#### IC Market Forecasts by Major World Regions

#### Market Forecasts by Device Type

- Transistors
- Processor Devices: MPUs, MCUs (4-bit, 8-bit, 16-bit, 32+-bit), DSPs
- Memory Devices: DRAM, SRAM, Flash, ROM/EPROM, EEPROM

- Logic Devices: Digital Bipolar, Standard Logic, Gate Arrays, Standard Cell & PLDs, Display Drivers & Touch Screen Controllers, Special Purpose Logic (Consumer, Computers, Communications, Automotive, Multipurpose & Other)

- Analog Devices: Amplifiers & Comparators, Interfaces, Voltage Regulators & References, Data Converters, Application-Specific Analog (Consumer, Computers, Communications, Automotive, Industrial & Other)

### Chapter 5: IC Packaging Market Analysis

#### Overview

#### IC Package Families

#### Worldwide IC Packaging Market

#### Total IC Packaging Market Forecasts

IC Packaging Market by I/O Count

Package Pricing Trends

#### IC Package Families Forecasts

- Dual In-Line Package Markets (DIP)
- Transistor Outline Package Markets (TO)
- Small Outline Transistor Package Market (SOT)
- Small Outline IC Markets (SOIC)
- Thin Small Outline Package Markets (TSOP)
- Chip Carrier Markets (CC)
- Quad Flat Pack Markets (QFP)
- Dual Flat Pack No Lead Markets (DFN)
- Quad Flat Pack No Lead Markets (QFN)
- Pin Grid Array Package Markets (PGA)
- Ball Grid Array Package Markets (BGA)
- Fine-Pitch Ball Grid Array Package Markets (FBGA)
- Wafer-Level Packaging Markets (WLP)
- Direct Chip Attached Markets (DCA)

#### Advanced IC Packaging

Multichip Packages

Fan-Out Wafer-Level Package (FOWLP)

Multirow QFN Packages

Flip Chip Interconnection

Through-Silicon Via Interconnect Solutions

### Chapter 6: OSAT Market and Strategy Analysis

#### Outsourcing in the Semiconductor Market

OSAT Market Forecasts, including: *Unit Shipments, Revenues, Package ASP*

# The Worldwide IC Packaging Market, 2018 Edition

## Table of Contents (continued)

### Chapter 7 OSAT Company Profiles

3D Plus	CORWIL Technology	Powertech Technology
Advotech	Deca Technologies	Shinko Electric
AIC Semiconductor	FlipChip Int'l	Signetics
Amkor Technology	Greatek Electronics	Sigurd Microelectronics
ANST China	Hana Microelectronics	SPiL
ASE	HANA Micron	SPEL Semiconductor
Azimuth	Interconnect Systems	STATS ChipPAC
Carsem	J-Devices	Tera Probe
Chant World Technology	Jiangsu Changjiang Electronics	Tianshui Huatian Tech
China Wafer Level CSP	Lingsen Precision Industries	TongFu Microelectronics
ChipMOS	nepes Corp.	Unisem
Cirtek	OSE	UTAC
CONNECTEC Japan	Palomar Technologies	Walton Advanced Engineering
		Xintec

Publish Date: April 2018 - 500+ Pages

### Order Form

#### Payment Method

Check in the amount of \$ \_\_\_\_\_ is enclosed.

Invoice per P.O. # \_\_\_\_\_

Please charge: Visa MasterCard American Express

Card # \_\_\_\_\_ Exp. \_\_\_\_\_

Name On Card \_\_\_\_\_

Signature \_\_\_\_\_ Date \_\_\_\_\_

Name \_\_\_\_\_

Title \_\_\_\_\_

Company \_\_\_\_\_

Address \_\_\_\_\_

City/State/Zip \_\_\_\_\_

Telephone \_\_\_\_\_

Fax \_\_\_\_\_

E-mail \_\_\_\_\_

**The Worldwide IC Packaging Market, 2018 Edition (Single-User License - PDF file)**

**\$3995**

**Add Extra Single-User Licenses (\$500 each) or Corporate License (\$1,500)**

**Returns:** No return privileges. **International Orders:** Must be prepaid, please contact us for payment arrangements.

#### **New Venture Research Corp.**

337 Clay St., Suite 101  
Nevada City, CA 95959

Tel: (530) 265-2004 Fax: (530) 265-1998

www.newventureresearch.com; info@newventureresearch.com

**Subtotal**

**Add Excel Spreadsheet of all Tables: \$1000**

**Add a printed copy of the report \$250**

**TOTAL**